

# High Sensitive Digital-Latch Hall Effect Sensor with Internal Pull-up Resistor

#### **FEATURES**

- Built-in pull-up resistor
- High chopping frequency
- Supports a wide voltage range
  - 2.5 to 24V
  - Operation from unregulated supply
- Wide operating temperature range
- Factory-programmed at end-of-line for optimum
- Reverse battery protection
- Over-voltage protection at all pins
- Solid-state reliability
- Small package
  - 3-pin SIP -(UA)
  - 3-pin SOT23 -(SO)

#### **APPLICATIONS**

- Power tools
- Flow meters
- Valve and solenoid status
- BLDC motors with sensors
- Proximity sensing
- Tachometers

#### DESCRIPTION

he SC224X family, produced with BiCMOS technology, is a chopper-stabilized Hall Effect Sensor that offers a magnetic sensing solution with superior sensitivity stability over temperature and integrated protection features.

Superior high-temperature performance is made possible through dynamic offset cancellation, which reduces the residual offset voltage normally caused by device over molding, temperature dependencies, and thermal stress. Each device includes on a single silicon chip a voltage regulator, Hall-voltage generator, small-signal amplifier, chopper stabilization, Schmitt trigger, and an output circuit.

An onboard regulator permits with supply voltages of 2.5 to 24V which makes the device suitable for a wide range of industrial and automotive applications

The device is available in a 3-pin SIP package (UA) and a 3-pin SOT-23 style package (SO). Both are lead (Pb) free, with 100% matte tin lead frame plating.



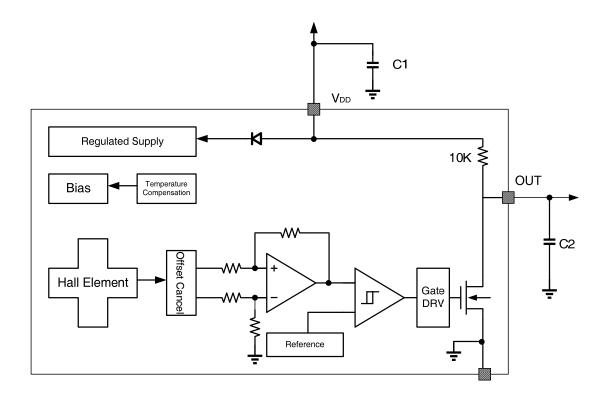


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# **BLOCK DIAGRAM**





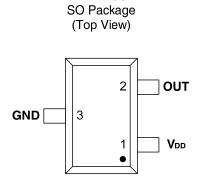
# **ORDERING INFORMATION**

Part Number	Packing	Mounting	Ambient, T <sub>A</sub>	B <sub>OP</sub> (Typ.	B <sub>RP</sub> (Typ.)
SC2242UA	Bulk,1000pieces/bag	3-pin SIP			
SC2242SO	Reel, 3000pieces/reel	3-pin SOT23	-40℃ to 150℃	+2.0mT	-2.0mT
SC2246UA	Bulk, 1000 pieces/bag	3-pin SIP			
SC2246SO	Reel, 3000pieces/reel	3-pin SOT23	-40℃ to 150℃	+4.0mT	-4.0mT
SC2248UA	Bulk, 1000 pieces/bag	3-pin SIP			
SC2248SO	Reel, 3000pieces/reel	3-pin SOT23	-40℃ to 150℃	+8.0mT	-8.0mT

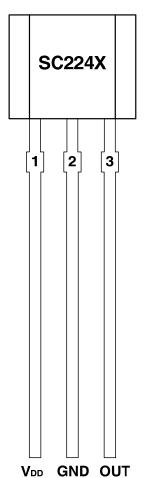


# **TERMINAL CONFIGURATION**

3-Terminal SIP **UA** Package (Top View)



3-Terminal SOT-23



Terminal				
Nome	Nun	nber	Туре	Description
Name	UA	SO		
V <sub>DD</sub>	1	1	PWR	2.5V ~24 V power supply
GND	2	3	Ground	Ground terminal
OUT	3	2	Output	Internal pull-up resistor



# **ABSOLUTE MAXIMUM RATINGS**

over operating free-air temperature range (unless otherwise noted) (1)

Parameter	Symbol	Min.	Max.	Units
Power supply voltage	$V_{DD}$	<b>-28</b> <sup>(2)</sup>	28	V
Output terminal voltage	V <sub>OUT</sub>	-0.5	28	V
Output terminal current sink	Isink	0	30	mA
Operating ambient temperature	TA	-40	150	${\mathbb C}$
Maximum junction temperature	TJ	-55	165	$^{\circ}$
Storage temperature	T <sub>STG</sub>	-65	175	$^{\circ}$

<sup>(1)</sup> Stresses above those listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

# **ESD PROTECTION**

Human Body Model (HBM) tests according to: standard AEC-Q100-002

Parameter	Symbol	Min.	Max.	Units
ESD-Protection	V <sub>ESD</sub>	-4	4	kV

# THERMAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	Rating	Units
R₀JA	UA Package thermal resistance	Single-layer PCB, with copper limited to solder pads	166	°C/W
R⊕JA	SO Package thermal resistance	Single-layer PCB, with copper limited to solder pads	228	°C/W

<sup>(2)</sup> Ensured by design.



# **OPERATING CHARACTERISTICS**

#### **Electric Characteristics**

over operating free-air temperature range ( $V_{\text{DD}} = 5.0V$ , unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V <sub>DD</sub>	Operating voltage (1)	$T_J < T_{J(Max.)}$	2.5		24	V
V <sub>DDR</sub>	Reverse supply voltage	I <sub>DD</sub> < -10mA, T <sub>A</sub> =25 °C	-28			V
IDD (off)	Operating aupply aurrent	V <sub>DD</sub> =2.5 to 24 V, T <sub>A</sub> =25℃	1.2	1.6	2.0	mA
I <sub>DD (on)</sub>	Operating supply current	V <sub>DD</sub> =2.5 to 24 V, T <sub>A</sub> =25℃	1.2	2.8	4.8	mA
ton	Power-on time			25	40	μS
Rup	Internal pull-up resistor		5.0	10	15	ΚΩ
I <sub>QL</sub>	Off-state leakage current	Output Hi-Z			3	μΑ
Б		V <sub>DD</sub> =5V, Io=10mA, T <sub>A</sub> =25℃		20		Ω
RDS (on)	FET on-resistance	V <sub>DD</sub> =5V, Io=10mA, T <sub>A</sub> =125°C		30		Ω
<b>t</b> d	Output delay time	B=BRP to BOP		15	25	μS
tr	Output rise time (10% to 90%)	R1=1Kohm Co=50pF		0.2	0.5	μS
t <sub>f</sub>	Output fall time (90% to 10%)	R1=1Kohm Co=50pF		0.1	0.2	μS

<sup>(1)</sup> Maximum voltage must be adjusted for power dissipation and junction temperature, see Thermal Characteristics



# **Magnetic Characteristics**

over operating free-air temperature range (unless otherwise noted)

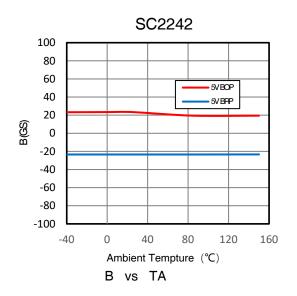
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
f <sub>BW</sub>	Bandwidth		20		1	kHz
SC2442	+2.0 / -2.0 mT					
Вор	Operated point		+0.5	+2.0	+3.5	mT
B <sub>RP</sub>	Release point	T <sub>A</sub> =-40°C to 150°C	-3.5	-2.0	-0.5	mT
Внуѕ	Hysteresis		2.0	4.0	6.0	mT
Во	Magnetic offset	Bo=(Bop+Brp)/2	-1.0	0	+1.0	mT
SC2446	+4.0 / -4.0 mT					
Вор	Operated point		+2.0	+4.0	+6.0	mT
B <sub>RP</sub>	Release point	T <sub>A</sub> =-40°C to 150°C	-6.0	-4.0	-2.0	mT
Внуѕ	Hysteresis		6.0	8.0	10.0	mT
Во	Magnetic offset	Bo=(Bop+Brp)/2	-2.0	0	+2.0	mT
SC2448	+8.0 / -8.0 mT					
Вор	Operated point		+6.0	+8.0	+10.0	mT
B <sub>RP</sub>	Release point	T <sub>A</sub> =-40°C to 150°C	-10.0	-8.0	-6.0	mT
B <sub>HYS</sub>	Hysteresis		14.0	16.0	18.0	mT
Во	Magnetic offset	Bo=(Bop+Brp)/2	-2.0	0	+2.0	mT

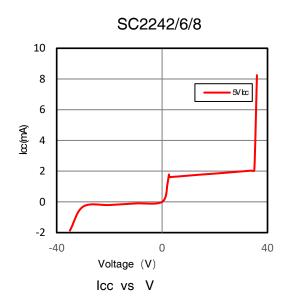
<sup>(1)1</sup>mT=10Gs

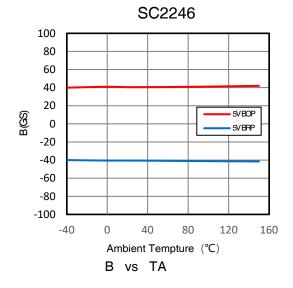
<sup>(2)</sup> Magnetic flux density, B, is indicated as a negative value for North-polarity magnetic fields, and as a positive value for South-polarity magnetic fields.

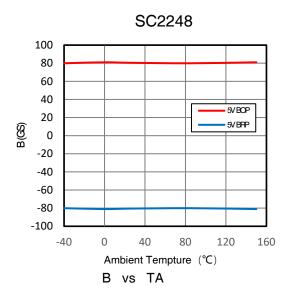


# **TYPICAL CHARACTERISTICS**











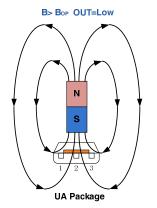
#### **FUNCTION DESCRIPTION**

The SC224X device is a chopper-stabilized Hall sensor with a digital latched output for magnetic sensing applications. The device can be powered with a supply voltage between 2.5 and 24V, and continuously survives continuous -28V reverse-battery conditions.

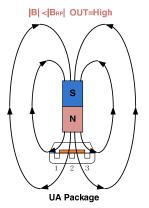
The output of SC224X switches low (turns on) when a magnetic field (South polarity) perpendicular to the Hall element exceeds the operate point threshold, Bop. After turn-on, the output is capable of sinking 20mA and the output voltage is V<sub>Q(sat)</sub>. When the magnetic field is reduced below the release point, B<sub>RP</sub>, the device output goes high (turns off). The difference in the magnetic operate and release points is the hysteresis, B<sub>HYS</sub>, of the device. This built-in hysteresis allows clean switching of the output even in the presence of external mechanical vibration and electrical noise.

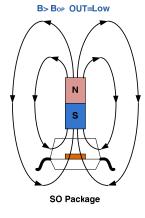
#### **Field Direction Definition**

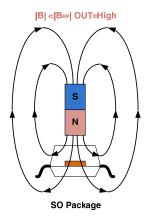
A positive magnetic field is defined as a South pole near the marked side of the package.



N=North pole, S=South pole







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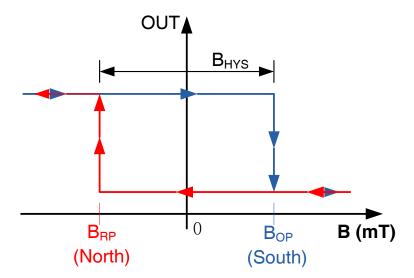
#### **Transfer Function**

Powering-on the device in the hysteresis region, less than  $B_{OP}$  and higher than  $B_{RP}$ , allows an indeterminate output state. The correct state is attained after the first excursion beyond  $B_{OP}$  or  $B_{RP}$ . If the field strength is greater than  $B_{OP}$ , then the output is pulled low. If the field strength is less than  $B_{RP}$ , the output is released.

Bop—magnetic threshold for activation of the device output, turning in ON (low) state

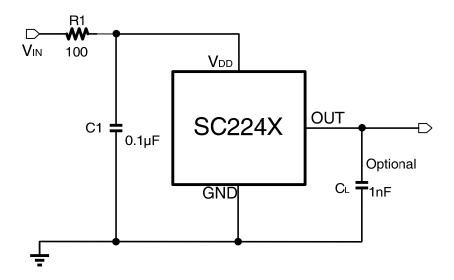
B<sub>RP</sub>—magnetic threshold for release of the device output, turning in OFF (high) state.

BHYS= BOP - BRP





#### TYPICAL APPLICATION



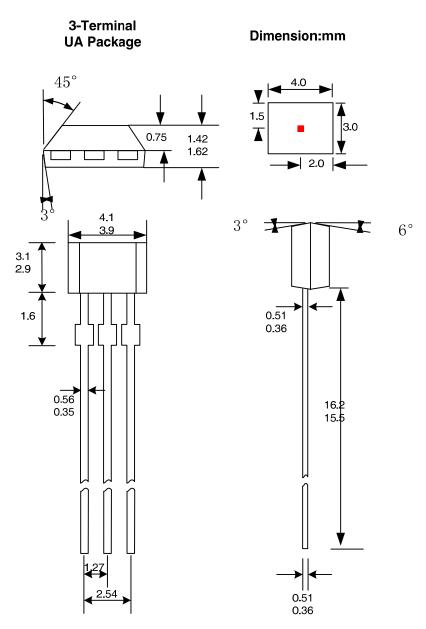
The SC224X contains an on-chip voltage regulator and can operate over a wide supply voltage range. In applications that operate the device from an unregulated power supply, transient protection must be added externally. For applications using a regulated line, EMI/RFI protection may still be required. It is recommended to shunt C1 capacitors to the ground near the chip  $V_{DD}$  power supply, with a typical value of 0. 1µF.At the same time in the external optional series resistor R1 their typical values for 100  $\Omega$ . The output capacitor  $C_L$  is used as the output filter, typically 1nF.

Select a value for  $C_L$  based on the system bandwidth specifications as,  $R=10k \Omega$ :

$$C_L = \frac{1}{2\pi \times R \times f (Hz)}$$



# **PACKAGE INFORMATION "UA"**



#### Notes:

- Exact body and lead configuration at vendor's option within limits shown.
- Height does not include mold gate flash.

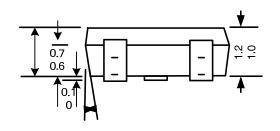
Where no tolerance is specified, dimension is nominal.

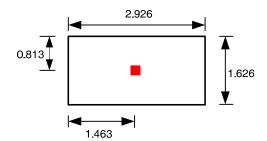


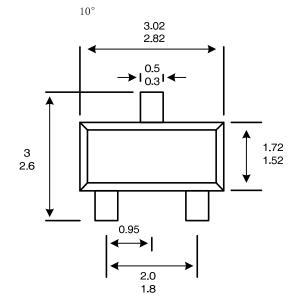
# **PACKAGE INFORMATION "SO"**

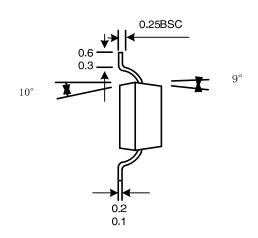
#### 3-Terminal **SO Package**

#### Dimension:mm









#### Notes:

- Exact body and lead configuration at vendor's option within limits shown.
- Height does not include mold gate flash.

Where no tolerance is specified, dimension is nominal.



# **REVISON HISTORY**

Revision	Date	Description
Rev0.1	2017-07-21	Preliminary datasheet
Rev2.3	2019-08-11	The final revision of old datasheet
Rev.A/1.0	2020-11-19	Unified datasheet format
Rev.A/1.1	2024-05-12	Update EC table